FORM PTO-1449 (REV.7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 850063.529	EXPRESS MAIL NO. EL615231713US
INFORMATION DISCLOSURE STATEMENT *(Use several sheets if necessary)*		APPLICANTS Shin Hwa Li and Annie Tissier	
		FILING DATE August 3, 2000	GROUP ART UNIT 2823

JC490 U.S. PTO 09/632388 08/03/00

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
KL	AA	6,001,731	12/99	Su et al.	438	633	
KL	AB	5,783,482	07/98	Lee et al.	438	624	
KL	AC	5,437,763	08/95	Huang	216	18	
KL	AD	5,518,962	05/96	Murao	438	624	
KL	AE	4,983,546	01/91	Hyun et al.	438	800	
KL	AF	5,567,661	10/96	Nishio et al.	438	631	
KL	AG**	5,169,491	12/92	Doan	156	636	
KL	AH**	5,560,802	10/96	Chisholm	156	636.1	
KL	AI**	5,5661,084	08/97	Kuo et al.	438	624	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
KL	AJ**	0599317A1 ✓	06/01/94	Europe	H01L	21/90		
KL	AK**	09223740 ✓	08/26/97	Japan (Abstract Only)	H01L	21/768		
KL	AL**	08255791 ✓	10/01/96	Japan (Abstract Only)	H01L	21/316		

OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

KL	AM		Wolf, Stanley, PhD., Silicon Processing for the VLSI Era, Volume 2-Process Integration, Lattice Press, Sunset Beach, Volume 2: 334-337, 1990.
KL	AN		Schaffer, W.J., et al., "BPSG Improves CPMP Performance for Deep Submicron Ics," Semiconductor International, 205-212, 1996.
KL	AO		Armstrong, W.E., et al., "A Scanning Electron Microscope Investigation of Glass Flow in MOS Integrated Circuit Fabrication," Journal of the Electrochemical Society, Volume 121, No. 2, 307-310, 1974.
KL	AP		Kerr, D.R., et al., "Stabilization of SiO2 Passivation Layers with P2O5," IBM Journal of Research and Development, Volume 8, No. 4, 376-384, 1964.

EXAMINER Kurt Eaton	DATE CONSIDERED 3/16/01

* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).

** = Copies of References Enclosed with this Application